

# WISES 2015

12° International Workshop on Intelligent Solutions in Embedded Systems

Ancona, Italy, October 29-30, 2015

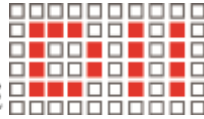
<http://www.dii.univpm.it/wises2015>

## Organization

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## Closing Remarks

### Previous editions

WISES 2003	June 27th, in Vienna, Austria
WISES 2004	June 25th, in Graz, Austria
WISES 2005	May 20th in Hamburg, Germany
WISES 2006	June 30th in Vienna, Austria
WISES 2007	June 21th in Madrid, Spain
WISES 2008	July 10th in Regensburg, Germany
WISES 2009	June 25th in Ancona, Italy
WISES 2010	July 8th in Heraklion, Crete, Greece
WISES 2011	July 7th in Regensburg, Germany
WISES 2012	July 5th in Klagenfurt, Austria
WISES 2013	September 10th in Pilsen, Czech Republic
WISES 2015	October 29, in Ancona, Italy

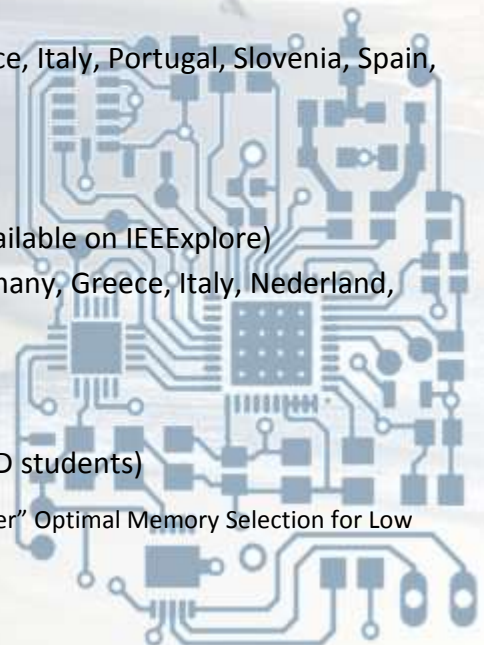
### Technical Program Committee

- 45 researchers from Academy and Industry
- 12 Nations: Albania, Austria, Brasil, France, Germany, Greece, Italy, Portugal, Slovenia, Spain, UK, USA

### Papers

- 29 Papers presented (published on the Proceedings and available on IEEEExplore)
- 92 Authors from 10 Nations: Albania, Austria, France, Germany, Greece, Italy, Nederland, Portugal, Slovenia, Spain
- 70% of authors are PhD students or young researchers
- 75% of speakers are PhD students or young researchers
- 101 attendee: inscriptions and registrations (students and PhD students)

Best paper award to Marcus Eggenberger and Martin Radetzki for the paper "Optimal Memory Selection for Low Power Embedded Systems"



# Acknowledgments

## Program Chair

Ermanno Cardelli, Università di Perugia, I (IEEE coordinator in Italy)

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Università Politecnica delle Marche: Rector Sauro Longhi and all the staff involved

## Invited Presentations

Leonel Sousa, INESC-ID, IST, Universidade de Lisboa (P)

Miltos Grammatikakis, TEIC, Crete (GR)

Antonis Papagrigorou, TEIC, Crete (GR)

## Participating Companies

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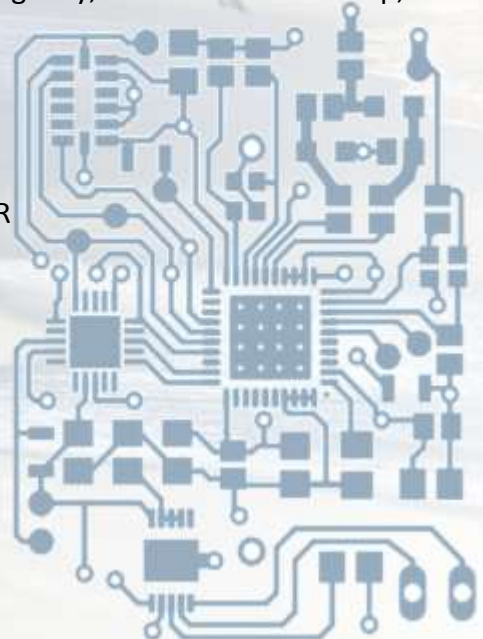
## Springer EURASIP Journal on Embedded Systems:

Leonel Sousa INESC-ID, IST, Universidade de Lisboa (P)

## Maserati for the Exposition

## All the Authors

## All the Participants



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